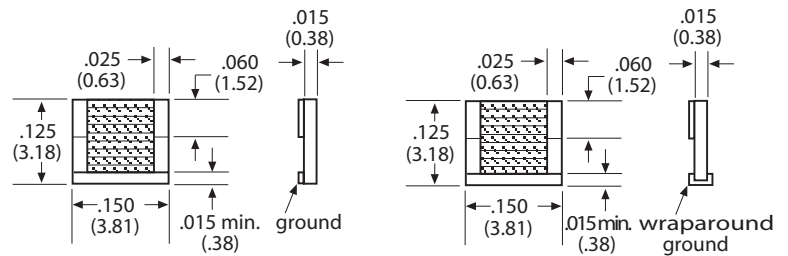


# LOW POWER CHIP ATTENUATORS



## FEATURES:

- DC to 8 GHz
- Temperature stable.
- Reliability programs to customer requirements.
- Custom sizes designed for special applications.
- Compatible with flow and reflow soldering.

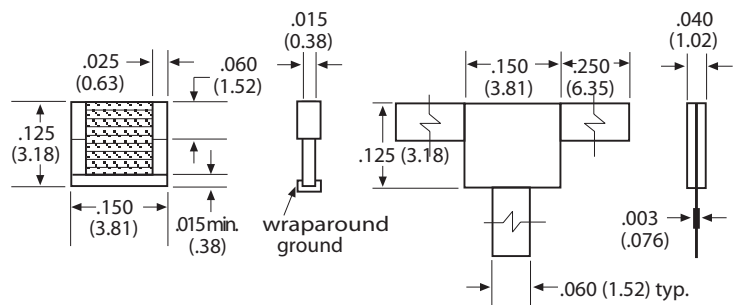


**Standard Singleface**

**STYLE W Ground Terminal Wraparound**

## GENERAL SPECIFICATIONS:

- IMPEDANCE: 50 Ohms.
- OPERATING TEMPERATURE: -55°C to +150°C. Exceeds applicable requirements of MIL-E-5400 and MIL-PRF-55342.
- ATTENUATION STABILITY: 0.0001 dB/DB/°C.
- TEMPERATURE COEFFICIENT: ±100 PPM/°C. (-55°C to +125°C with 25°C as reference). Other temperature coefficients available.
- POWER RATING: The power rating is 1 Watt from 25°C to 85°C derated linearly to zero at 150°C. The chip can be used at a higher power level with adequate heat sinking.
- RESISTIVE ELEMENTS: Proprietary film.
- TERMINALS: Platinum Silver or Tin over Nickel.
- SUBSTRATE: 96% Alumina.
- COVER: Epoxy or Alumina.
- TABS: **Beryllium** Copper, Gold Plated.



**STYLE W3 3 Terminal Wraparound**

**STYLE C Tabs & Cover**

## PERFORMANCE SPECIFICATIONS:

(Test methods per MIL-PRF-55342)

TEST	REQUIREMENTS
Thermal Shock	±(.25% +0.05 ohm)
Low Temperature Operation	±(.25% +0.05 ohm)
Short Time Overload	±(.1% +0.005 ohm)
High Temperature Exposure	±(.5% +0.005 ohm)
Moisture Resistance	±(.5% +0.05 ohm)
Life	±(1% +0.05 ohm)
Solderability	95% min. coverage
Termination Adhesion	15 grams min.

## MICROSTRIP CONFIGURATION:

dB VALUE	DC - 4 GHz		DC - 8 GHz	
	ATTEN. Sens. dB	VSWR (max.)	ATTEN. Sens. dB	VSWR (max.)
1 to 6	±0.5	1.25	±0.5	1.35
7 to 9	±0.5	1.25	±0.5	1.35
10 to 12	±0.75	1.25	±1.0	1.35
13 to 14	±0.75	1.25	±0.5-2	1.35
15 to 16	±1.0	1.25	±0.5-3	1.35
17 to 18	±1.0	1.25	±0.5-3	1.35
19 to 20	±1.0	1.25	±0.5-4	1.35

**1 WATT**  
**Part Number**  
**RNCA**  
**Db**      **Style**